

Revision History	
Revision	Notes
A	* Built & Tested

SCR1	SCR0	Slew Rate
0	0	Slow
0	1	Medium Slow
1	0	Medium Fast
1	1	Fast

Operation Mode	
High	Normal Mode
Low	Low Power Mode

Regulator Enable	
High	On
Low	Off

5Vg Output Enable	
High	On
Low	Off

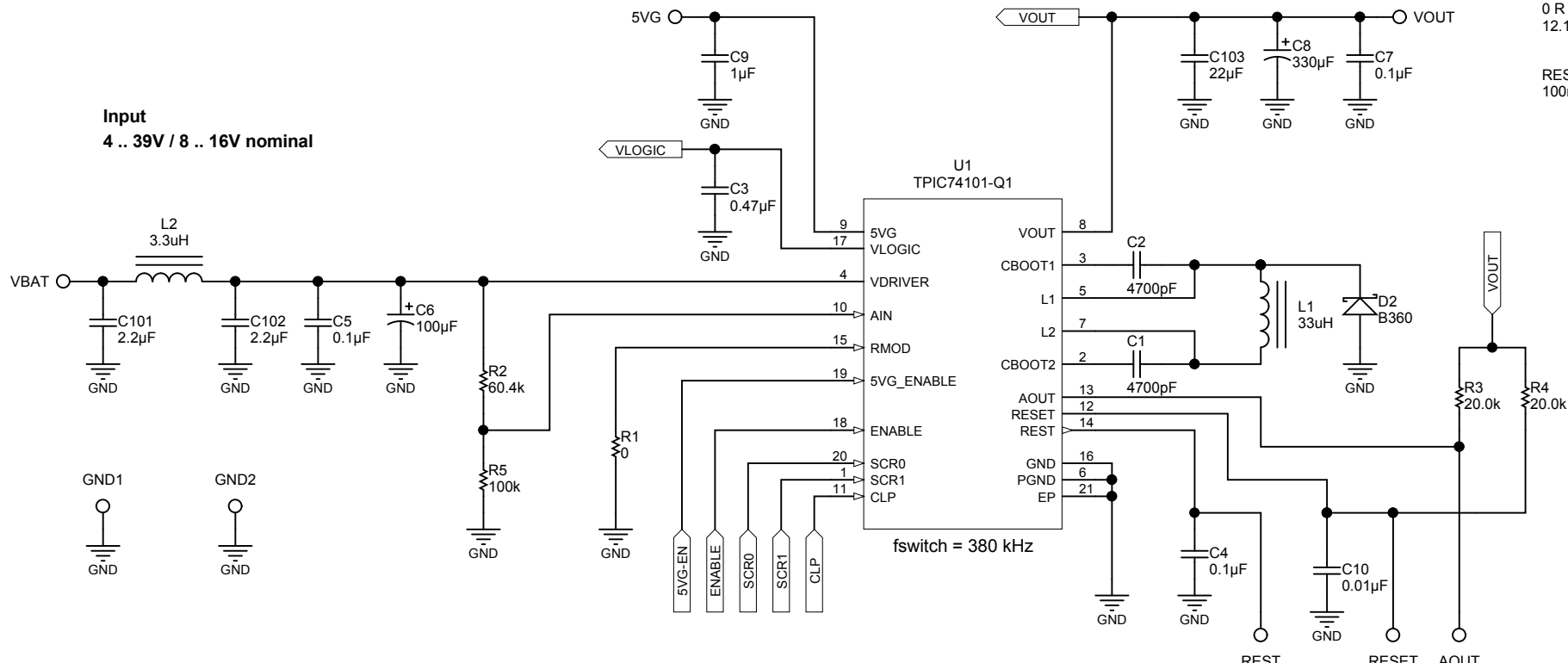
AIN - Alarm Input	
< 2.3V (< 3.7V)	AOUT Low
> 2.5V (> 4.0V)	AOUT High

AOUT - Alarm Output	
High	Vin Ok
Low	Vin Low

RMOD - Frequency Modulation	
0 R	0 kHz
12.1 k	28 kHz

REST - Reset Timer Delay	
100nF	100ms

**Output**  
**5.0V @ 500mA**



**Design Notes**

- \* Designators fit TPIC74101-EVM
- \* Parts with RefDes > 100 have no footprint on PCB

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Number: PMP10170 Rev: A  
 SVN Rev: Not in version control  
 Drawn By: KNielsen  
 Engineer: Matthias Ulmann

Designed for: Public Release	Mod. Date: 4/8/2015
Project Title: Automotive Buck-Boost Boost	
Sheet Title: Power Train	
Assembly Variant: Variant name not interpreted	Sheet: 1 of 1
File: PMP10170RevA_SchDoc	Size: A4
Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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